

<b>Notice of References Cited</b>			Application No. <b>08/704,467</b>		Applicant(s) <b>Gallagher et al</b>	
			Examiner <b>M. Kohn 10/1/97</b>		Group Art Unit	Page <b>1</b> of <b>1</b>
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*	DOCUMENT NO.	DATE	NAME		CLASS	SUBCLASS
A	<b>4,434,084</b>	<b>2/28/84</b>	<b>Hicks et al</b>		<b>252</b>	<b>512</b>
B	<b>5,088,189</b>	<b>2/18/92</b>	<b>Brown</b>		<b>29</b>	<b>840</b>
C	<b>5,136,365</b>	<b>8/4/92</b>	<b>Pennisi et al</b>		<b>357</b>	<b>72</b>
D						
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FOREIGN PATENT DOCUMENTS						
*	DOCUMENT NO.	DATE	COUNTRY	NAME	CLASS	SUBCLASS
N	<b>58-42651</b>	<b>3/12/83</b>	<b>JP</b>	<b>Tokyo Elect.</b>		
O						
P						
Q						
R						
S						
T						
NON-PATENT DOCUMENTS						
*	DOCUMENT (Including Author, Title, Source, and Pertinent Pages)					DATE
U	<b>Lee et al "Organic Acids and Acid Anhydrides as Curing Agents"</b>					
	<b>Epoxy Resins, McGraw-Hill Book Co, 1957 (No mark) pp 115-24.</b>					<b>1957</b>
V						
W						
X						

\* A copy of this reference is not being furnished with this Office action.  
(See Manual of Patent Examining Procedure, Section 707.05(a).)